UltraSORB® Cleanroom wipers
for sensitive surfaces

Description

UltraSORB® is a highly absorbent wiper that combines excellent ESD characteristics with class 100 cleanliness. Due to its sponge-like wiping capability, fiber-free construction and ability to resist shedding of particles due to abrasion, it is the perfect choice for stencil, thick film screen and medical device wiping applications. It's unique pore structure allows for controlled solvent transfer to screen and metal masks to aid in the removal of solder paste, conductive adhesives and thick film inks. Ideal for cleaning metal masks used to print LTCC components, capacitors, EL, OLED and plasma display panels. Due to its ability to conform to metal mask surfaces, **UltraSORB®** enables excess paste to be thoroughly removed while minimizing abrasion to the emulsion.

Application advantages

- High density construction and sponge-like properties make it ideal for particle sensitive metal mask cleaning operations.
- Open-cell, soft foam structure allows for controlled transfer of solvent to optimize cleaning of thick film applications.
- Excellent abrasion resistance and fluid retention enables fiber-free wiping of thick film screens and hot molds.
- Will not interfere with the curing of elastomers, platinium cured silicones or adhesives.
- Allows for thorough removal of solder paste from stencil face and aperture.
- Uniform application of solvent to achieve "kill" ratios on aseptic surfaces.
- Excellent abrasion resistance to reduce particle generation in-use.
- Static dissipative to minimize the risk of ESD events.
- Pyrogen-free for medical device wipe-down.
- 100% fiber-free
- Available in small sizes to reduce cost in applications such as catheter wipe down.

Article-numbers:

Art.-no.:	**Sizes:** (thickness/size)	**Packaging unit:**
RT4644/50	.109“ x 4“ x 4“	50 pcs
RT4666/50	.109“ x 6“ x 6“	50 pcs
RT4669/50	.109“ x 9“ x 9“	50 pcs

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Chemical resistance
(Resistance to ASTM D543 / 30-day saturation)

Chemical	Temp.	% wt. change	Observation		Chemical	Temp.	% wt. change	Observation
Acetone	23°C 50°C	-0,2 -7,8	unaffected softened		Methanol	23°C 50°C	-1,6 -6,3	unaffected softened
Sodium Hydroxide	23°C 50°C	-21,7 -50,9	discolored, brittle Severe attack		MEK	23°C 50°C	-1,0 -5,9	unaffected softened
Ammonia hydroxide	23°C 50°C	-1,8 -18,9	unaffected softened		Mineral Oil	23°C 50°C	+35,5 +44,1	unaffected
Benzene	23°C 50°C	-0,5 -7,8	unaffected softened		Oils/Fats	23°C 50°C	+18,5 +19,1	unaffected
Ethyl Alcohol	23°C 50°C	-0,3 -5,8	unaffected softened		Phos Acid 10%	23°C 50°C	-1,0 -6,6	unaffected softened
Ethyl Ether	23°C 50°C	-0,4 -9,9	unaffected softened		Sulfuric Acid .02N	23°C 50°C	+0,2 -3,6	unaffected softened
Ethyl Acetate	23°C 50°C	-0,7 -5,1	unaffected softened		Detergent	23°C 50°C	+6,2 +7,6	unaffected softened
Freon	23°C 50°C	-0,3 -4,8	unaffected softened		Toulene	23°C 50°C	+0,8 -5,1	unaffected softened
HCl 1%	23°C 50°C	-4,0 -12,9	discolored, brittle severe attack		Tricloro-ethane	23° 50°C	+0,5 -7,9	unaffected softened
IPA 2-propenol	23°C 50°C	-0,8 -6,9	unaffected		Xylene	23°C 50°C	0 -5,1	unaffected softened

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